

**WHAT IS CLAIMED IS:**

*Sub A1* → A system for recording data in a multi-board solid-state storage system, comprising:

- i. at least one main board that includes a processing system for enabling interaction with a host system;
- ii. at least one memory board separate from said main board, such that each said at least one memory board carries at least part of the storage system's primary solid-state components array used for data storage; and
- iii. for each said memory board, at least one secondary non-volatile memory device, located on said each memory board, and containing system information related to said each memory board.

2. The system of claim 1, wherein said main board includes:

- a) at least a portion of said primary solid-state components array; and
- b) at least one respective secondary non-volatile memory device containing system information related to said main board.

3. The system of claim 1, wherein, for each said at least one memory board, each said at least one secondary non-volatile memory device optionally stores information selected from the group consisting of:

- (a) At least one faulty location record for said primary solid-state components array located on said board;

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(b) at least one description of a geometry of said primary solid-state components array;

(c) manufacturing information for said board; and

(d) security information for data stored on said board

4. A method for recording system information in a multi-board solid state storage system, comprising the steps of:

i. Placing a respective secondary non-volatile memory device onto each board of the multi-board solid state storage system;

ii. For each board, recording system information of said each board on said secondary non-volatile memory device thereof; and

iii. Storing said system information in said secondary non-volatile memory device of said each board.

5. The method of claim 4, further comprising:

iv. performing direct actions selected from the group consisting of testing, adding, connecting and replacing said boards.

6. The method of claim 4, wherein said system information includes data selected from the group consisting of faulty locations records, geometry information, manufacturing information and security information.